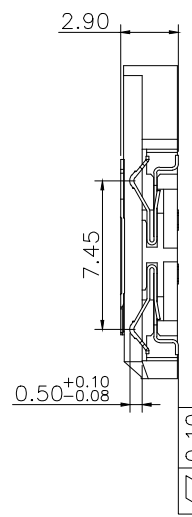
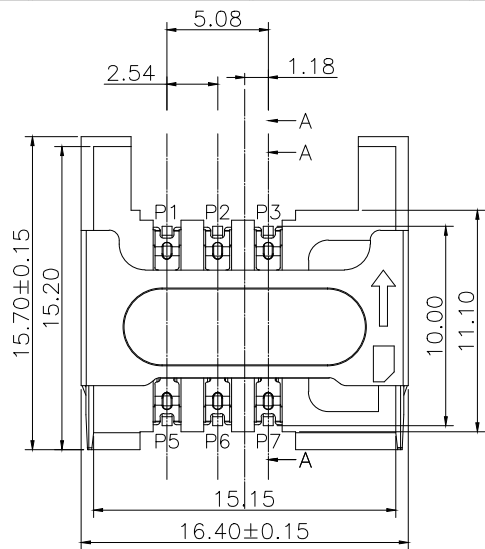
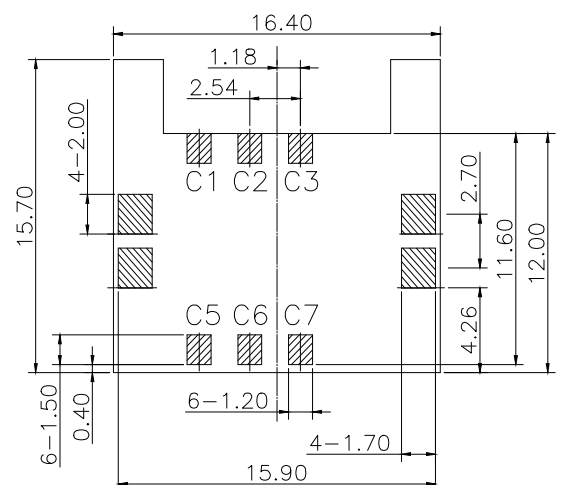


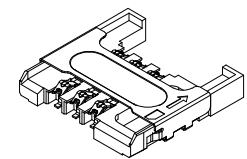
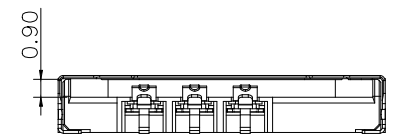
REV.	ECN.NO.	MODIFY.CONTENT	DATE
A0		NEW	2017/10/16
A1		更新料号	2018/11/28



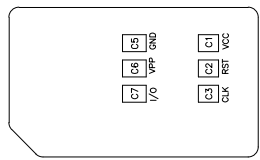
SECTION A-A



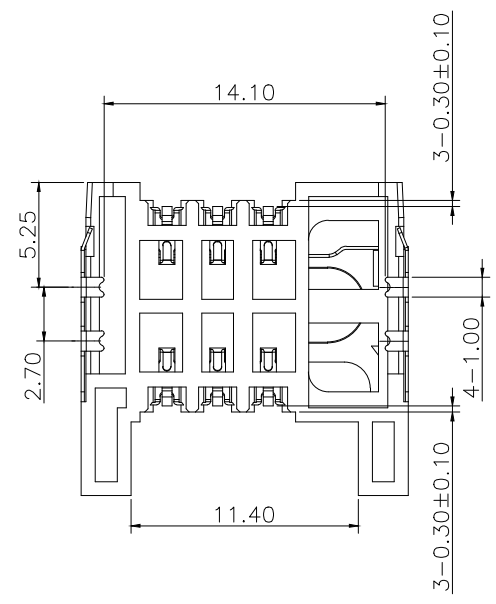
RECOMMENDED PCB LAYOUT TOL:(±0.05)



NOTES:
 1) MATERIAL:
 HOUSING: LCP+30%G.F UL 94V-0 BALCK
 CONTACT: SUS 201 T=0.15H
 SHELL: C5210 T=0.15H
 2) FINISH :
 CONTACT: Au 1u" PLATED ON CONTACT AREA;
 AU 1u" PLATING ON SOLDER TAILS,
 WITH ENTIRE CONTACT UNDERPLATED NICKEL 30u"MIN
 SHELL: WITH ENTIRE CONTACT UNDERPLATED NICKEL 50u"MIN
 Au 1u" PLATED ON SOLDER TAILS
 3) PART NO.:



SIM 示意图
芯片面朝下视图



PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C2:RST
P3#	C3:CLK
P4#	C5:GND
P5#	C6:VPP
P6#	C7:I/O

GENERAL TOLERANCE	DWG NO.	APPD:	朱全	Scale	1:1
X.±0.45	x.'±5°	CHKD:		UNIT	mm
.X±0.35	.x'±2°	DR:	彭善平		
.XX±0.25	.xx'±1°	Date	2017/10/16		
.XXX±0.15	.xxx'±0.5°				
SHEET 1/1					

C - S 2 0 6 2 9 0 A 1 - 1

S:SIM卡
 T:T-F卡
 U:Micro/MIMI USB
 B:Battery
 D:SD卡
 H:HDMI
 J:JACK

pin 数 06P:6PIN
 08P:8PIN
 05P:5PIN
 03P:3PIN

290:产品高度2.90H

端子电镀:
 1: 镀半金银1u"
 2: 镀半金银3u"
 3: 镀半金银5u"
 4: 镀半金银10u"
 5: 镀半金银15u"